

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims:

1. (Currently Amended) A smooth surface copper foil for lamination to a dielectric substrate, the copper foil comprising:

a peel strength enhancement coating deposited on a smooth surface of the copper foil having an  $R_z$  of less than about  $1\text{ }\mu\text{m}$  to be laminated to said dielectric substrate, the peel strength enhancement coating consisting essentially of a metal and metal oxide mixture, the metal and metal oxide mixture being formed from one or more of: chromate, tungstate and molybdate ~~vanadium, niobium, tantalum, chromium, molybdenum, tungsten, manganese, technetium, and rhenium.~~

2.- 5. (Canceled)

6. (Currently Amended) An article comprising:

a dielectric substrate;

a copper foil having a smooth surface with an  $R_z$  less than about  $1\text{ }\mu\text{m}$  laminated to the dielectric substrate; and

a peel strength enhancement coating disposed between the smooth surface of the copper foil and the dielectric substrate, said peel strength enhancement coating being a mixture of a metal and a metal oxide with said metal selected from the group consisting of one or more of chromate, tungstate and molybdate ~~vanadium, niobium, tantalum, chromium, molybdenum, tungsten, manganese, technetium, and rhenium,~~ wherein the copper foil exhibits less than or equal to 10% loss of peel strength when measured ~~[[m4easured]]~~ in accordance with IPC-TM-650 Method 2.4.8.5 using a 1/8 inch test specimen after being immersed in 4N HCl at 60°C for 6 hours.

7. – 12. (Canceled)